

# EP1345HSPD-57.000M

[Click part number to visit Part Number Details page](#)

## REGULATORY COMPLIANCE (Data Sheet downloaded on Aug 31, 2016)


[Click badges to download compliance docs](#)

Regulatory Compliance standards are subject to updates by governing bodies. Click the badges to download the latest compliance docs for this part number directly from Ecliptek.



## ITEM DESCRIPTION

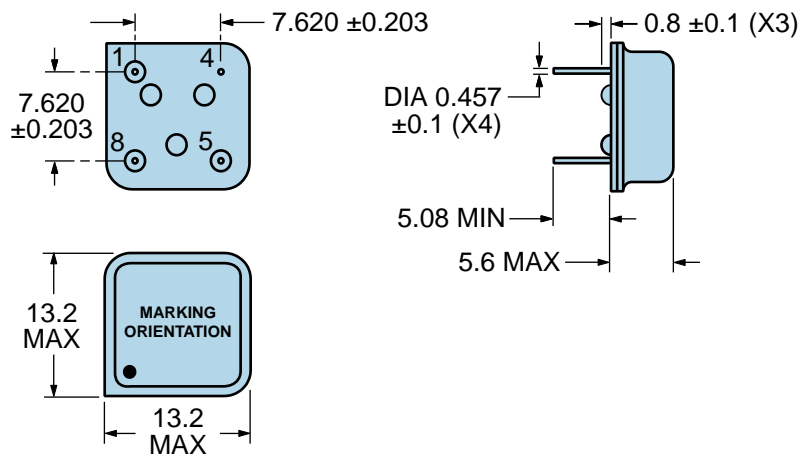
Quartz Crystal Clock Oscillators XO (SPXO) LVCMOS (CMOS) 3.3Vdc 8 Pin DIP Metal Thru-Hole 57.000MHz  $\pm$ 50ppm -20°C to +70°C

## ELECTRICAL SPECIFICATIONS

Nominal Frequency	57.000MHz
Frequency Tolerance/Stability	$\pm$ 50ppm Maximum (Inclusive of all conditions: Calibration Tolerance at 25°C, Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, First Year Aging at 25°C, Shock, and Vibration)
Aging at 25°C	$\pm$ 5ppm/year Maximum
Operating Temperature Range	-20°C to +70°C
Supply Voltage	3.3Vdc $\pm$ 10%
Input Current	28mA Maximum (Unloaded)
Output Voltage Logic High (Voh)	Vdd-0.4Vdc Minimum (IOH = -8mA)
Output Voltage Logic Low (Vol)	0.4Vdc Maximum (IOL = +8mA)
Rise/Fall Time	4nSec Maximum (Measured at 20% to 80% of waveform)
Duty Cycle	50 $\pm$ 10(%) (Measured at 50% of waveform)
Load Drive Capability	15pF Maximum
Output Logic Type	CMOS
Pin 1 Connection	Power Down (Disable Output: Logic Low)
Pin 1 Input Voltage (Vih and Vil)	70% of Vdd Minimum to enable output, 20% of Vdd Maximum to disable output, No Connect to enable output.
Disable Current	16mA Maximum (Pin 1 = Ground)
Standby Current	20 $\mu$ A Maximum (Pin 1 = Ground)
Peak to Peak Jitter (tPK)	100pSec Maximum, 60pSec Typical
RMS Period Jitter (tRMS)	13pSec Maximum, 10pSec Typical
Start Up Time	10mSec Maximum
Storage Temperature Range	-55°C to +125°C

## ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Lead Integrity	MIL-STD-883, Method 2004
Mechanical Shock	MIL-STD-202, Method 213, Condition C
Resistance to Soldering Heat	MIL-STD-202, Method 210
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010
Vibration	MIL-STD-883, Method 2007, Condition A

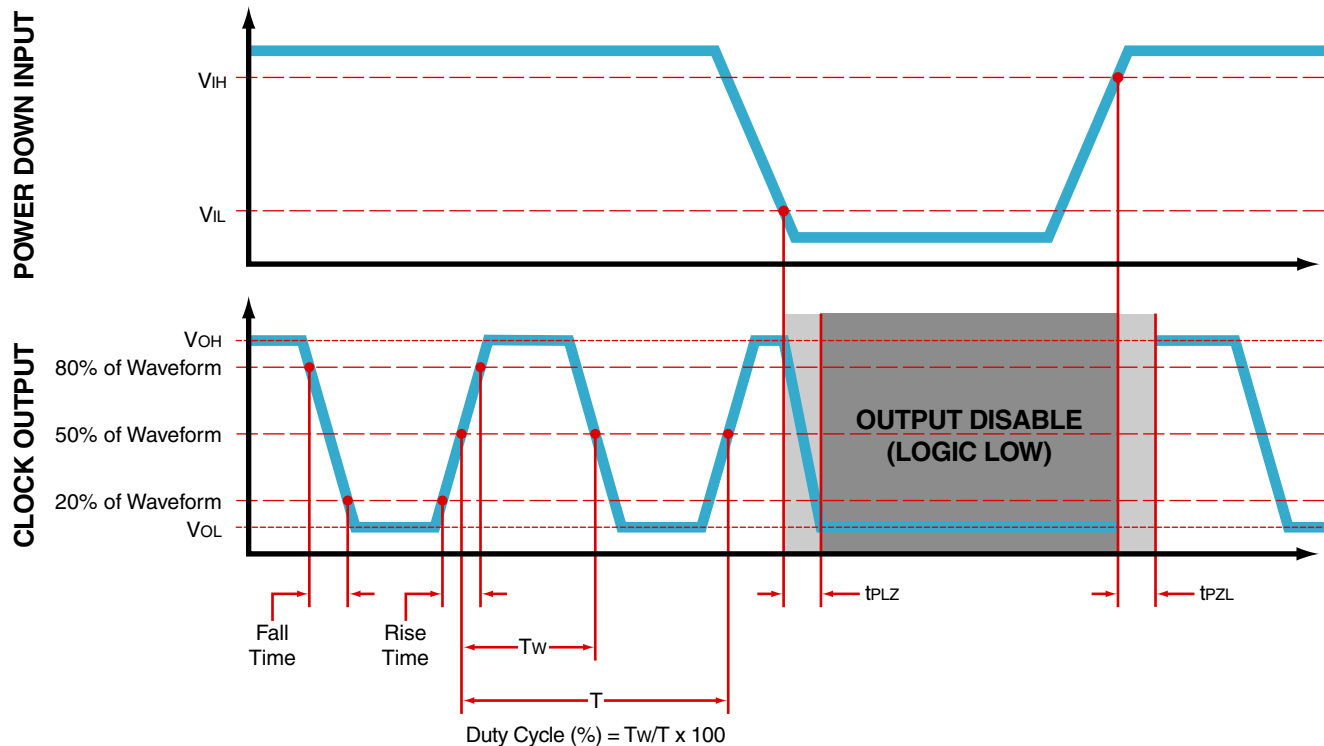
**EP1345HSPD-57.000M**
[Click part number to visit Part Number Details page](#)
**MECHANICAL DIMENSIONS (all dimensions in millimeters)**

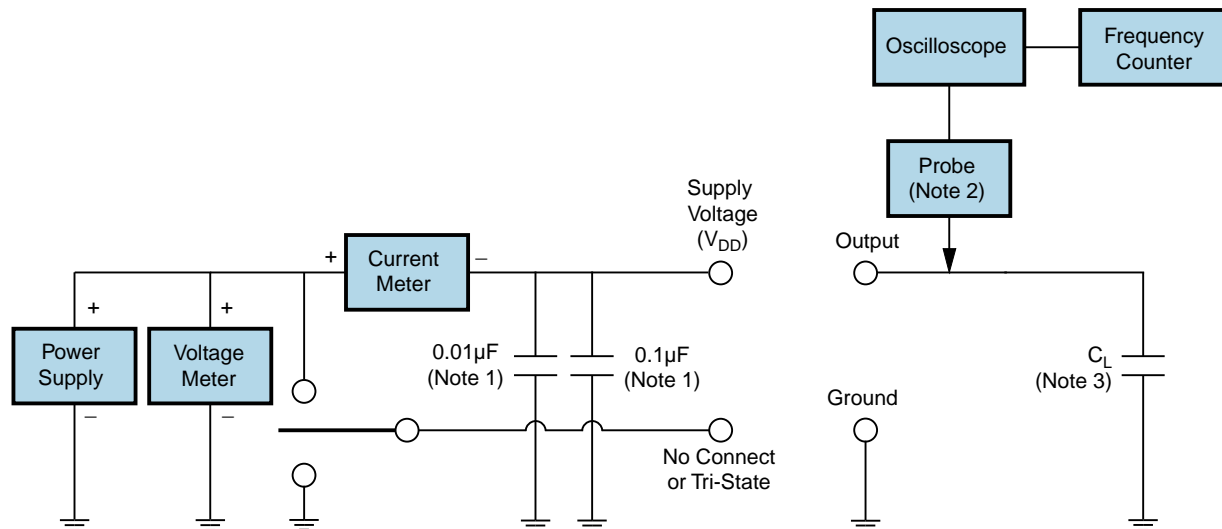
PIN	CONNECTION
1	Power Down (Logic Low)
4	Case/Ground
5	Output
8	Supply Voltage

LINE	MARKING
1	<b>ECLIPTEK</b>
2	<b>EP13PD</b> <i>EP13=Product Series</i>
3	<b>57.000M</b>
4	<b>XXYZZ</b> <i>XX=Ecliptek Manufacturing Code</i> <i>Y=Last Digit of the Year</i> <i>ZZ=Week of the Year</i>

# EP1345HSPD-57.000M [Click part number to visit Part Number Details page](#)

## OUTPUT WAVEFORM & TIMING DIAGRAM



**Test Circuit for CMOS Output**

Note 1: An external  $0.1\mu\text{F}$  low frequency tantalum bypass capacitor in parallel with a  $0.01\mu\text{F}$  high frequency ceramic bypass capacitor close to the package ground and  $V_{DD}$  pin is required.

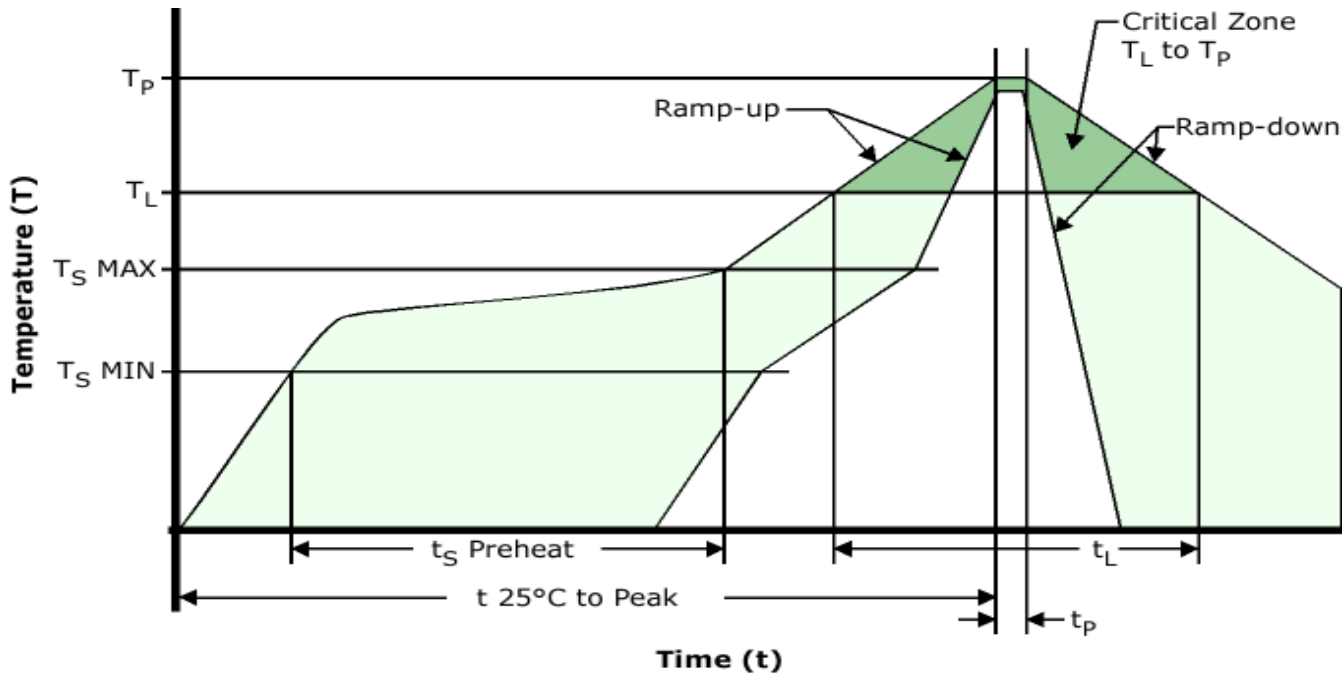
Note 2: A low capacitance ( $<12\text{pF}$ ), 10X attenuation factor, high impedance ( $>10\text{Mohms}$ ), and high bandwidth ( $>300\text{MHz}$ ) passive probe is recommended.

Note 3: Capacitance value  $C_L$  includes sum of all probe and fixture capacitance.

# EP1345HSPD-57.000M

[Click part number to visit Part Number Details page](#)

## Recommended Solder Reflow Methods



### High Temperature Solder Bath (Wave Solder)

$T_S$ MAX to $T_L$ (Ramp-up Rate)	3°C/Second Maximum
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#### Preheat

- Temperature Minimum ( $T_S$ MIN)	150°C
- Temperature Typical ( $T_S$ TYP)	175°C
- Temperature Maximum ( $T_S$ MAX)	200°C
- Time ( $t_s$ MIN)	60 - 180 Seconds

Ramp-up Rate ( $T_L$ to $T_P$ )	3°C/Second Maximum
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#### Time Maintained Above:

- Temperature ( $T_L$ )	217°C
- Time ( $t_L$ )	60 - 150 Seconds

Peak Temperature ( $T_P$ )	260°C Maximum for 10 Seconds Maximum
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Target Peak Temperature ( $T_P$ Target)	250°C +0/-5°C
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Time within 5°C of actual peak ( $t_p$ )	20 - 40 Seconds
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Ramp-down Rate	6°C/Second Maximum
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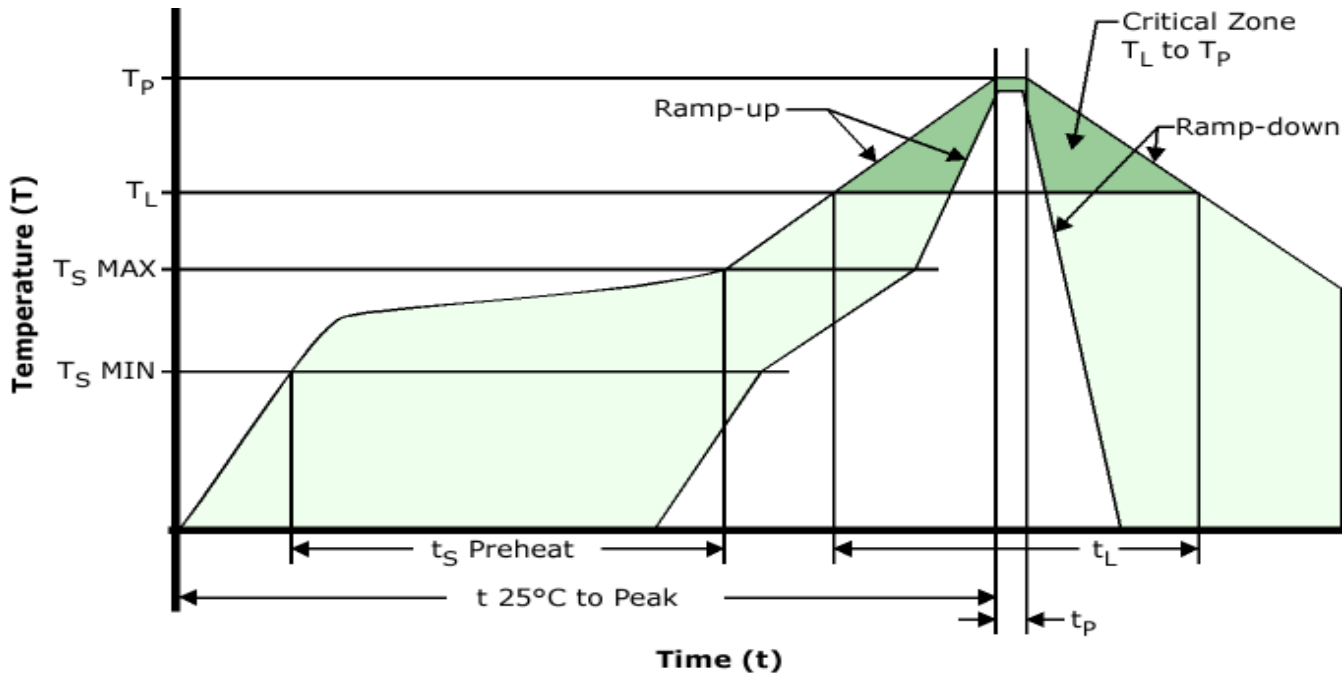
Time 25°C to Peak Temperature (t)	8 Minutes Maximum
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Moisture Sensitivity Level	Level 1
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# EP1345HSPD-57.000M

[Click part number to visit Part Number Details page](#)

## Recommended Solder Reflow Methods



### Low Temperature Infrared/Convection 185°C

$T_S$ MAX to $T_L$ (Ramp-up Rate)	5°C/Second Maximum
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#### Preheat

- Temperature Minimum ( $T_S$ MIN)	N/A
- Temperature Typical ( $T_S$ TYP)	150°C
- Temperature Maximum ( $T_S$ MAX)	N/A
- Time ( $t_s$ MIN)	60 - 120 Seconds

Ramp-up Rate ( $T_L$ to $T_P$ )	5°C/Second Maximum
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#### Time Maintained Above:

- Temperature ( $T_L$ )	150°C
- Time ( $t_L$ )	200 Seconds Maximum

Peak Temperature ( $T_P$ )	185°C Maximum
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Target Peak Temperature ( $T_P$ Target)	185°C Maximum 2 Times
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Time within 5°C of actual peak ( $t_p$ )	10 Seconds Maximum 2 Times
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Ramp-down Rate	5°C/Second Maximum
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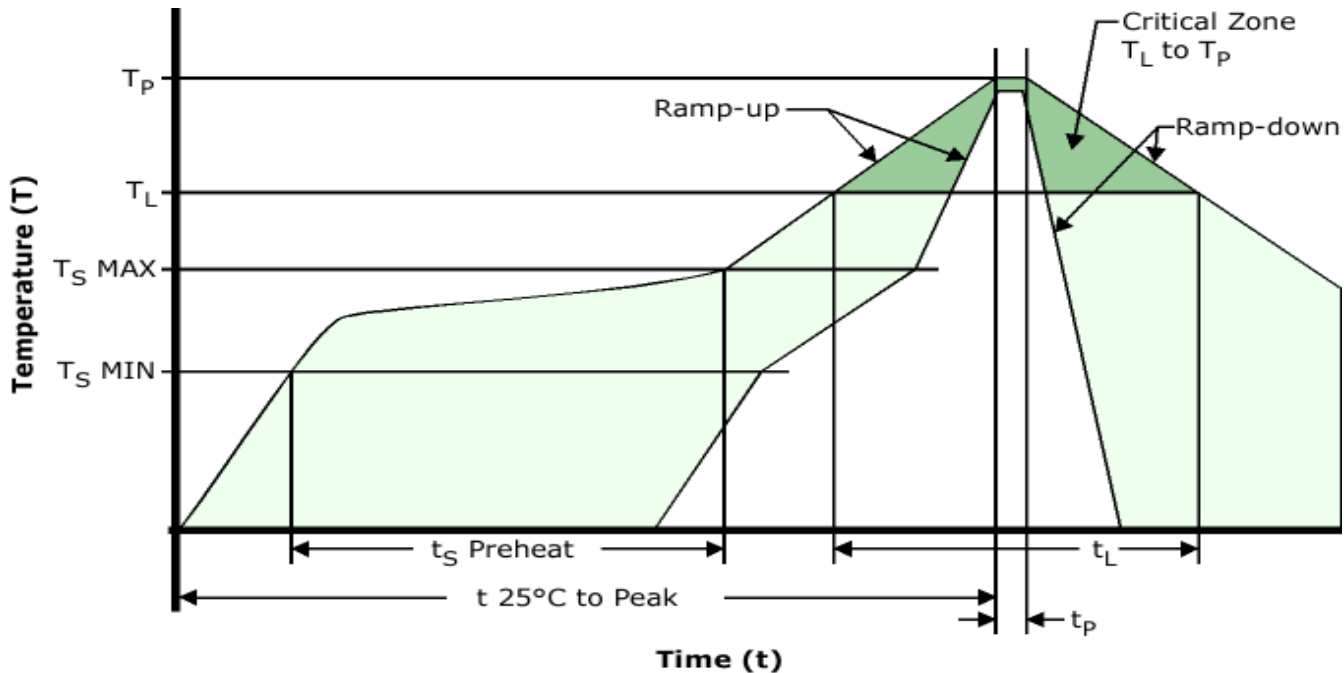
Time 25°C to Peak Temperature (t)	N/A
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Moisture Sensitivity Level	Level 1
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## Recommended Solder Reflow Methods



### Low Temperature Solder Bath (Wave Solder)

$T_S$ MAX to $T_L$ (Ramp-up Rate)	5°C/Second Maximum
<b>Preheat</b>	
- Temperature Minimum ( $T_S$ MIN)	N/A
- Temperature Typical ( $T_S$ TYP)	150°C
- Temperature Maximum ( $T_S$ MAX)	N/A
- Time ( $t_s$ MIN)	30 - 60 Seconds
Ramp-up Rate ( $T_L$ to $T_P$ )	5°C/Second Maximum
<b>Time Maintained Above:</b>	
- Temperature ( $T_L$ )	150°C
- Time ( $t_L$ )	200 Seconds Maximum
Peak Temperature ( $T_P$ )	245°C Maximum
Target Peak Temperature ( $T_P$ Target)	245°C Maximum 1 Time / 235°C Maximum 2 Times
Time within 5°C of actual peak ( $t_p$ )	5 Seconds Maximum 1 Time / 15 Seconds Maximum 2 Times
Ramp-down Rate	5°C/Second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1

### Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum.

### High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum.